

Filename: PMP7236 REV\_A\_bom.xls

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## PMP7236 REV\_A BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	open	Capacitor, Ceramic, 2kV, X7R, 10%	1812	Std	Std
1	C2	220uF	Capacitor, Aluminum, 16V, 20%	0.328 x 0.354 inch	EEVFK1C221P	Panasonic
1	C7	47nF	Capacitor, Ceramic, 100V, X7R, 10%	0805	Std	Std
1	C12	22uF	Capacitor, Aluminum, 16V, 20%	0.328 x 0.354 inch	EEEFK1J220B	Panasonic
1	C14	100nF	Capacitor, Ceramic, 100V, X7R, 10%	0603	C2012X7R2A104K	TDK
1	C16	1nF	Capacitor, Ceramic, 100V, X7R, 10%	0805	Std	Std
1	C17	100pF	Capacitor, Ceramic, 500V, X7R, 10%	0805	Std	Std
1	C18	470pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	Std	Std
1	C20	100pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	Std	Std
1	C22	330pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	Std	Std
1	C23	22nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C24	100pF	Capacitor, Ceramic, 50V, COG, 10%	0603	Std	Std
1	C25	open	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
2	C15 C19	100nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
2	C21 C26	1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	Std	Std
4	C3-6	22uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	Std	Std
4	C8-11	1uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	C3225X7R2A105K	TDK
1	D2	MBRS160T3	Diode, Schottky, 1A, 60V	SMB	MBRS160T3	OnSemi
1	D3	MMSD914	Diode, Switching, 100-V, 200-mA, 225-mW	SOD-123	MMSD914T1	On Semi
1	D100	12V	Diode, Zener, 12-V, 350-mW	SOT-23	BZX84C12-7-F	Fairchild
1	D101	MBRS2200	Diode, Schottky, 2A, 200V	SMC	MBRS2200	On Semi
1	J1	ED1514	Terminal Block, 2-pin, 6A, 3.5mm	0.27 x 0.25	ED1514	OST
1	J2	ED120/2DS	Terminal Block, 2-pin, 15A, 5.1mm	0.40 x 0.35 inch	ED120/2DS	OST
1	L1	10uH	Inductor, SMT, 3.8A, 38milliohm	0.51x0.37 inch	DO3316P-103L	Coilcraft
1	Q3	CSD18531Q5A	MOSFET, NChannel, 60V, 22A, 4.3milliohm	QFN-8 POWER	CSD18531Q5A	TI
1	R1	1k	Resistor, Chip, 1/2W, 5%	2010	Std	Std
1	R5	3.3	Resistor, Chip, 1/8W, 1%	1206	Std	Std
1	R6	243k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	0	Resistor, Chip, 1/16W, 1%	0805	Std	Std
1	R10	330	Resistor, Chip, 1/2W, 5%	2010	Std	Std
1	R12	220	Resistor, Chip, 1/4 watt, 5%	1206	Std	Std
1	R14	0.01	Resistor, Chip, 1/4W, 5%	1210	Std	Std
1	R15	0	Resistor, Chip 1/4 watt, ±1%	1206	Std	STD

1	R17	32.4k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R21	182k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R23	56.2k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R27	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R28	open	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R100	15k	Resistor, Chip, 1/8W, 1%	1206	Std	Std
1	R101	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R11 R22 R25	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R13 R26	1.00k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R18 R20	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R19 R24	10.0k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	T1	10 uH	Transformer, ±10%	0.530 x 0.700 inch	See schematic	EPCOS
8	TP1 TP3-5 TP7-10	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
3	TP2 TP6 TP11	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	TPS40210DGQ	IC, 4.5V-52V I/P, Current Mode Boos Controller	DGQ10	TPS40210DGQ	TI
1	U2	TCMT1107	IC, Photocoupler, CTR = 80% - 160%	MF4	TCMT1107	Vishay
1	U3	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
  2. These assemblies must be clean and free from flux and all contaminants.  
Use of no clean flux is not acceptable.
  3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
  4. Ref designators marked with an asterisk (\*\*\*) cannot be substituted.  
All other components can be substituted with equivalent MFG's components.

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